SQM30010EL

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RoHS

COMPLIANT HALOGEN

FREE

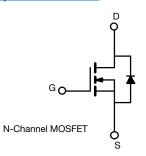
Automotive N-Channel 30 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	30			
$R_{DS(on)}$ (Ω) at V_{GS} = 10 V	0.00135			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 V$	0.00175			
I _D (A)	120			
Configuration	Single			
Package	TO-263			

FEATURES

- TrenchFET® power MOSFET
- · Package with low thermal resistance
- 100 % R_g and UIS tested
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	30	V	
Gate-source voltage		V _{GS}	± 20	V	
Continuous drain current ^a	T _C = 25 °C	- I _D	120		
	T _C = 125 °C		120		
Continuous source current (diode conduction) ^a		ا _S	120	А	
Pulsed drain current ^b		I _{DM}	360		
Single pulse avalanche current	L = 0.1 mH	I _{AS}	72		
Single pulse avalanche energy	L = 0.1 mm	E _{AS}	259	mJ	
Maximum power dissipation ^b	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $P_{\rm D}$	375	W		
	T _C = 125 °C	гD	125	٧V	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	C°	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-ambient	PCB mount ^c	R _{thJA}	40	°C/W	
Junction-to-case (drain)		R _{thJC}	0.4	0/10	

Notes

- a. Package limited
- b. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- c. When mounted on 1" square PCB (FR4 material)

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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static								
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$		30	-	-	v	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$		1.5	2.0	2.5		
Gate-source leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$		-	-	± 100	nA	
Zero gate voltage drain current	I _{DSS}	$V_{GS} = 0 V$	V _{DS} = 30 V	-	-	1		
		$V_{GS} = 0 V$	$V_{DS} = 30 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	μA	
		$V_{GS} = 0 V$	$V_{DS} = 30 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$	-	-	800	μA	
On-state drain current ^a	I _{D(on)}	$V_{GS} = 10 V$	$V_{DS} \ge 5 V$	100	-	-	Α	
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 40 A	-	0.00110	0.00135	Ω	
		V _{GS} = 10 V	I _D = 40 A, T _J = 125 °C	-	-	0.00191		
		$V_{GS} = 10 V$	I _D = 40 A, T _J = 175 °C	-	-	0.00220		
		V _{GS} = 4.5 V	I _D = 35 A	-	0.00143	0.00175	Ω	
Forward transconductance b	9 _{fs}	V _{DS}	= 15 V, I _D = 40 A	-	233	-	S	
Dynamic ^b					•			
Input capacitance	C _{iss}	V _{GS} = 0 V	V _{DS} = 15 V, f = 1 MHz	-	20 090	28 000	pF	
Output capacitance	C _{oss}			-	7000	9500		
Reverse transfer capacitance	C _{rss}			-	540	750		
Total gate charge ^c	Qg		$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 50 \text{ A}$	-	295	450	nC	
Gate-source charge ^c	Q _{gs}	V _{GS} = 10 V		-	59	-		
Gate-drain charge ^c	Q _{gd}			-	59	-		
Gate resistance	Rg	f = 1 MHz		0.5	1.11	1.7	Ω	
Turn-on delay time ^c	t _{d(on)}	V_{DD} = 15 V, R _L = 0.2 Ω I _D \cong 50 A, V _{GEN} = 10 V, R _g = 1 Ω		-	30	45		
Rise time ^c	tr			-	240	360	ns	
Turn-off delay time ^c	t _{d(off)}			-	98	150		
Fall time ^c	t _f			-	44	70		
Source-Drain Diode Ratings and Chara	cteristics b							
Pulsed current ^a	I _{SM}			-	-	360	А	
Forward voltage	V _{SD}	I _F = 60 A, V _{GS} = 0 V		-	0.8	1.5	V	
Body diode reverse recovery time	t _{rr}	I _F = 35 A, di/dt = 100 A/μs		-	96	195	ns	
Body diode reverse recovery charge	Q _{rr}			-	185	370	nC	
Reverse recovery fall time	ta			-	48	-		
Reverse recovery rise time	t _b			-	48	-	ns	
Body diode peak reverse recovery current	I _{RM(REC)}			-	-3.4	_	Α	

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %

b. Guaranteed by design, not subject to production testing

c. Independent of operating temperature

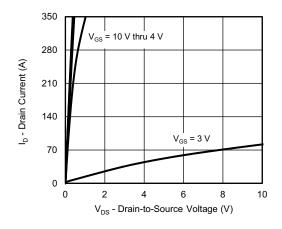
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

2

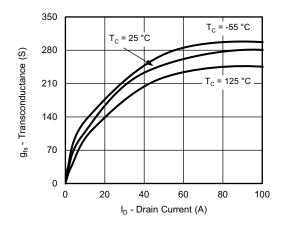


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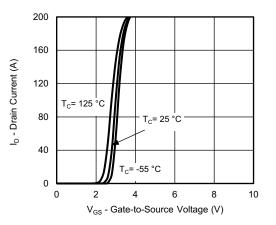
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



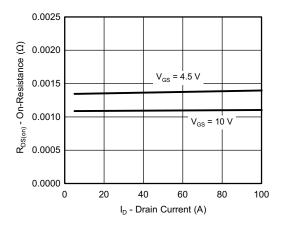
Output Characteristics



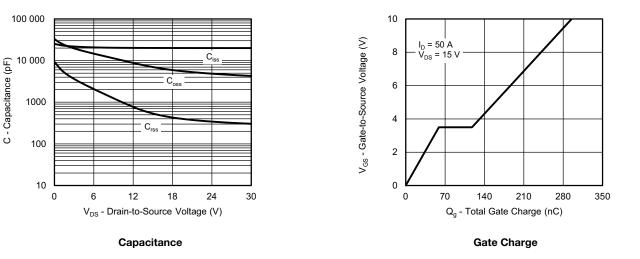
Transconductance



Transfer Characteristics



On-Resistance vs. Drain Current



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3

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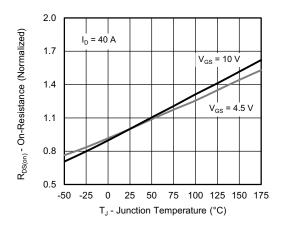
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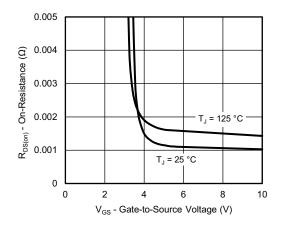
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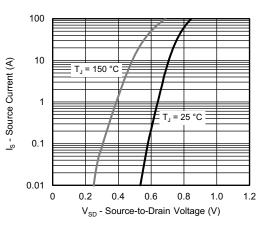
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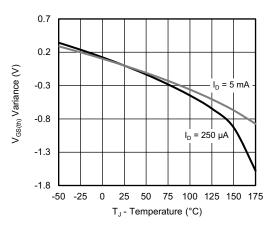
On-Resistance vs. Junction Temperature



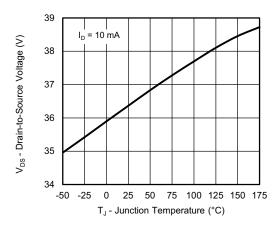
On-Resistance vs. Gate-to-Source Voltage



Source Drain Diode Forward Voltage







Drain Source Breakdown vs. Junction Temperature

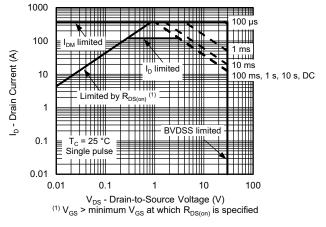
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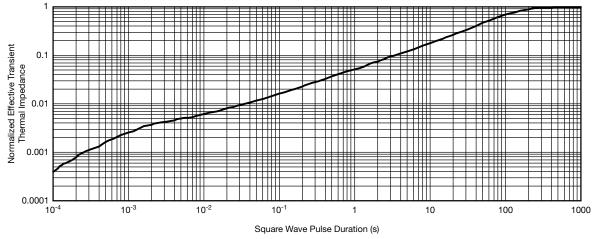
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THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)





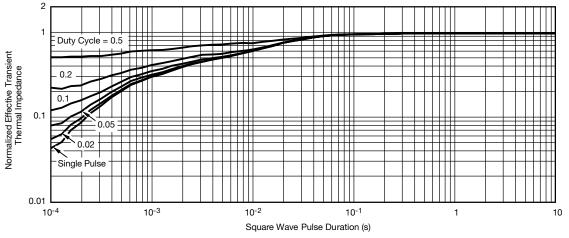


Normalized Thermal Transient Impedance, Junction-to-Ambient



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THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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6



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